

*AMENDMENTS TO THE CLAIMS*

This listing of claims replaces all prior versions, and listings, of claims in the application.

Claims 1 and 13 (Cancelled).

14. (New) A method of forming leads of a packaged semiconductor device that includes a package having opposed first and second sides and first and second leads extending outwardly from the first and second sides of the package, respectively, the method comprising:

adjusting separation between first and second bottom dies to receive the package of the packaged semiconductor device between the first and second bottom dies, the first and second bottom dies having respective top surfaces that include oblique portions;

placing the package of the packaged semiconductor device between the first and second bottom dies with the first and second lead proximate the top surfaces of the first and second bottom dies, respectively;

moving at least one of the first and second bottom dies and first and second top dies having respective bottom surfaces with oblique portions complementary to the top surfaces of the first and second bottom dies, respectively, toward each other;

clamping the first and second leads between the top and bottom surfaces of the first top and bottom dies and between the second top and bottom dies, respectively, and

urging the first top and bottom dies and the second top and bottom dies together, thereby forming the first and second leads, and, simultaneously, producing lateral forces through contact of the complementary top and bottom surfaces and the first and second leads, and, in response to the lateral forces, moving the first and second top dies laterally, relative to the first and second bottom dies, thereby changing separation between the first and second top dies.

15. (New) The lead forming method according to claim 14, wherein the top surfaces of the first and second bottom dies apply cam forces to the first and second top dies, and the first and second top dies roll laterally in response to the cam forces.

16. (New) The lead forming method according to claim 15, including, before clamping the first and second leads, adjusting separations between the top surfaces of the first and second bottom dies and the bottom surfaces of the first and second top dies.

17. (New) The lead forming method according to claim 14, including, before clamping the first and second leads, adjusting separations between the top surfaces of the first and second bottom dies and the bottom surfaces of the first and second top dies.

18. (New) The lead forming method according to claim 14, wherein the top surfaces of the first and second bottom dies include respective separate first and second portions for contacting proximal and distal portions of the first and second leads, respectively, the method including, before clamping the first and second leads, adjusting the second portions of the top surfaces of the first and second bottom dies to adjust an angle at which the first and second leads are formed.

19. (New) The lead forming method according to claim 14 including supporting the package of the packaged semiconductor device between the first and second bottom dies before clamping the first and second leads, without directly placing the first and second leads on the top surfaces of the first and second bottom dies.

20. (New) The lead forming method according to claim 14, including, before clamping the first and second leads, detecting the separation between the first and second bottom dies and adjusting the separation between the first and second bottom dies in response to the separation detected.

21. (New) The lead forming method according to claim 14, wherein the package of the packaged semiconductor device includes opposed third and fourth sides, transverse to the first and second sides, and third and fourth leads extending outwardly from the third and fourth sides, respectively, the method comprising:

after forming the first and second leads, releasing the first and second leads from the first and second top and bottom dies and removing the first and second leads from the first and second top and bottom dies;

rotating the packaged semiconductor device 90°, placing the third and fourth leads opposite the top surfaces of the first and second bottom dies, respectively; and

repeating the moving, clamping, and urging with the third and fourth leads, thereby forming the third and fourth leads.